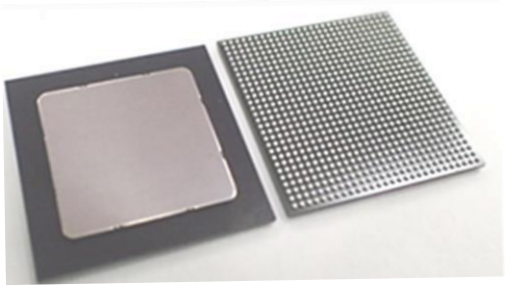
Lidded Flip-Chip Package

Introduction

SHINKO provides a high-heat-dissipation flip-chip package that radiates thermals to a heat spreader (lid) from the back side of an IC chip through the TIM (Thermal Interface Material).

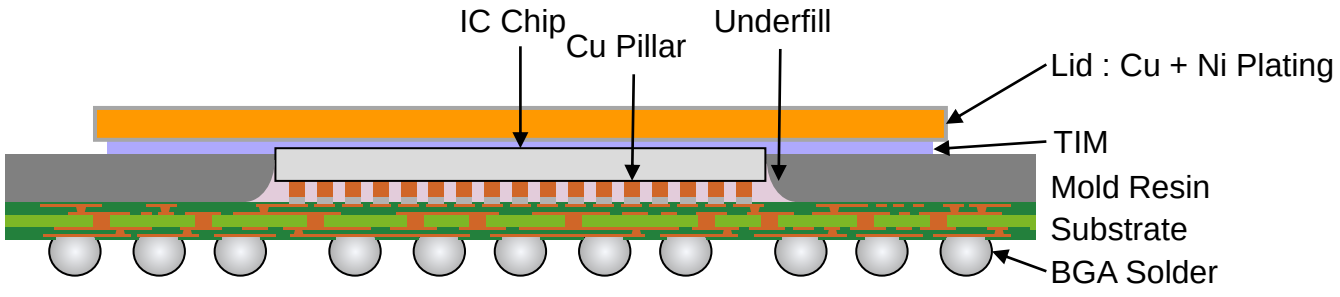


Features

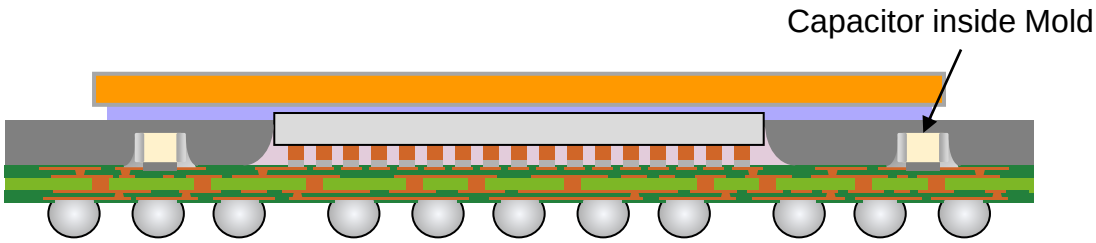
- With the back side of the chip being exposed, heat generated from the IC chip is dissipated directly to the lid.
- High quality and long-term supply are achieved by using an in-house leadframe as the lid.
- Various types of flip-chip bonding technologies with high density IC chips are available
- A molded, exposed chip structure under the lid enables low package warpage with a thin substrate
- Lidded package with thin substrate (such as 200 µm thickness core material) is available.
- Used in up to AEC-Q100 Grade 2 capable automotive devices

Structure

■ Standard Lidded Flip-Chip Package



■ Option : Built-in component (under development)



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